

## 5G-TESTBED



### BRIEF DESCRIPTION

5G-Testbed for industrial equipment via wireless connections.

### RESEARCH SERVICES

- Wafer level microfabrication 8" capability
- Die/chip level microfabrication capability
- Minimal resolutions  $\leq 10 \mu\text{m}$  (Remark: depends on the substrate and the ink type)
- 2.5D (3D) heterogeneous structures (e.g. combination of metal and dielectric)
- Suitable to print over multi-material 3D substrates (Si wafers, polymers, ceramic, etc.)
- Adjustment ejection flow rate (i.e. ejection frequency) is possible by many orders of magnitude
- 5G-Testbed for industrial equipment via wireless connections.  
for experimental performance evaluation and configuration optimization (under real life conditions)
- Research & Development  
of application protocols, TSN integration and positioning
- Training & Support  
from theoretical aspects to roll out and deployment challenges

### METHODS & EXPERTISE ON THE RESEARCH INFRASTRUCTURE

SAL offers services around Wireless standards.

### CONTACT

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